

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type*
 Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sat, Aug 27, 2011 03:10 AM
Contact Name * David Lancaster	Title - Contact Product Ecology	Phone - Contact * 801-562-7455	Email - Contact * david.lancaster@fairchildsemi.com
Authorized Representative * David Lancaster	Title - Representative Product Ecology	Phone - Representative * 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
FDS6680	FDS6680	SOIC-8 (CuBW)			INTERNAL PENANG	0.088	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	1	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
RoHS Directive 2002/95/EC	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).</p> <p>Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.</p>		
RoHS Declaration *	1 - Item(s) does not contain RoHS restricted substances per the definition above	Supplier Acceptance * Accepted
<p>Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.</p> <p>Exemption List Version EL-2006/690/EC 0</p>		

Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SOIC-8 (CuBW)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Silicon	7.100	Supplier		Silicon	7.100	7440-21-3	80757
Die Attach	Adhesive	0.718	Supplier		Acrylic Resin	0.154	54208-63-8	1752
			Supplier		Silver	0.564	7440-22-4	6411
Encapsulation	Epoxy	39.400	B	Antimony/Antimony Compounds	Antimony Trioxide	0.788	1309-64-4	8963
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	0.394	6386-73-8	4481
			Supplier		Carbon Black	0.296	1333-86-4	3361
			Supplier		Epoxy Resin	11.426	29690-82-2	129963
			Supplier		Silica	26.496	60676-86-0	301379
Lead Frame	Copper Alloy	38.600	Supplier		Copper	37.531	7440-50-8	426886
			Supplier		Iron	0.926	7439-89-6	10537
			Supplier		Phosphorus	0.015	7723-14-0	176
			Supplier		Silver	0.077	7440-22-4	878
			Supplier		Zinc	0.050	7440-66-6	571
Plating	Pb-Free Solder	2.000	Supplier		Tin	2.000	7440-31-5	22749
Wire Bond	Copper Wire	0.100	Supplier		Copper	0.100	7440-50-8	1137